






Board Stack Report

Stack Up		Layer Stack			
Layer	Board Layer Stack	Name	Material	Thickness	Constant
1		Top Paste			
2		Top Overlay			
3		Top Solder	Solder Resist	0,005mm	3,5
4		Top Layer	Copper	0,042mm	
5		Dielectric 1	FR-4 (tg > 150 Celsius)	0,100mm	4,2
6		Mid-Layer 1	Copper	0,035mm	
7		Dielectric 2	FR-4 (tg > 150 Celsius)	0,240mm	4,2
8		Mid-Layer 2	Copper	0,035mm	
9		Dielectric 3	FR-4 (tg > 150 Celsius)	0,130mm	4,2
10		Mid-Layer 3	Copper	0,035mm	
11		Dielectric 4	FR-4 (tg > 150 Celsius)	0,240mm	4,2
12		Mid-Layer 4	Copper	0,035mm	
13		Dielectric 5	FR-4 (tg > 150 Celsius)	0,130mm	4,2
14		Mid-Layer 5	Copper	0,035mm	
15		Dielectric 6	FR-4 (tg > 150 Celsius)	0,240mm	4,2
16		Mid-Layer 6	Copper	0,035mm	
17		Dielectric 7	FR-4 (tg > 150 Celsius)	0,100mm	4,2
18		Bottom Layer	Copper	0,042mm	
19		Bottom Solder	Solder Resist	0,005mm	3,5
20		Bottom Overlay			
21		Bottom Paste			
	Height : 1,484mm				